

CICMT 2010 Tabletop Exhibit Application

IMAPS ID # _____ ACerS ID# _____

Company _____

Contact _____

Address _____

City/State _____

Zip _____ Country _____

Phone _____ Fax _____

E-mail _____

Webpage _____

Cost: **Thru 3/20/10** **After 3/20/10**

IMAPS/ACerS Member* \$550 \$650

Non-Member \$700 \$800

*Corporate Member

Yes, our company will purchase one tabletop space.

Yes, our company will participate in the CD-ROM*.
(free-of-charge) *Submit electronic file (Word or PDF) to abell@imaps.org not later than March 20, 2010.

Our check is enclosed for the full rental amount of \$_____ payable to IMAPS in US funds.

Please charge my credit card the full amount of _____.

AMEX VISA MC Diners Discover

Card # _____

Exp Date: _____

Card Holder's Name _____

Signature _____

Card Billing Address (if different than above)

Cancellation Policy: Booth cancellations made before 3/20/10 will receive a refund minus \$100 handling fee. Booths cancelled after 3/20/10 will not be refunded.

Sponsored by:



**IMAPS -
International Microelectronics
And Packaging Society**

and

**ACerS -
The American Ceramic Society**



**IMAPS
611 2nd Street, N.E.
Washington, D.C. 20002
Ph: 202-548-4001
Fax: 202-548-6115
imaps@imaps.org
www.imaps.org**

*Everything in electronics between
the chip and the system!*

Reserve your booth online at
www.cicmt.org
or complete this form and
fax it back to
202-548-6115.

CICMT 2010

**International Conference
on
Ceramic Interconnect
and
Ceramic Microsystems
Technologies**

**Tabletop
Exhibit
Application**

**Exhibition
April 19 & 20, 2010**

**Conference
April 18 - 21, 2010**



www.cicmt.org

CICMT 2010

IMAPS/ACerS

6th International Conference and Exhibition on Ceramic Interconnect and Ceramic Microsystems Technologies

Goal:

The Ceramic Interconnect and Ceramic Microsystems Technologies (CICMT) conference brings together a diverse set of disciplines to share experiences and promote opportunities to accelerate research, development and application of ceramic interconnect and ceramic microsystems technologies. This international conference features ceramic technology for both Microsystems and Interconnect applications in a dual-track technical program. The Ceramic Interconnect topics focus on cost effective and reliable high performance ceramic interconnect products for hostile thermal and chemical environments in the automotive, aerospace, de-fense/security, and communication industries. The Ceramic Microsystems topics focus on emerging applications and new products that exploit the ability of 3-D ceramic structures to integrate interconnect/packaging with microfluidic, optical, micro-reactor and sensing functions. Tape casting, thick film hybrid, direct write and rapid prototyping technologies are common to both topical areas, with emphasis on material, processes, prototype development, advanced design and application opportunities

Co-Sponsored By:

IMAPS Japan

Ceramics Society of Japan

Ferroelectric Committee of Japan (FMA)

Japan Society of Applied Physics

MRS-Japan

AIST

www.cicmt.org

Exhibits:

Ann Bell, IMAPS

abell@imaps.org

EXHIBITION INFORMATION

Exhibit Hours

Tuesday, April 19 12:00 am - 7:00 pm
*Lunch, Refreshment Breaks & a Reception
will be held in the Exhibit Area.*

Wednesday, April 20 10:00 am - 4:00 pm
*Lunch and Refreshment Breaks will be held
in the Exhibit Area.*

Installation Hours:

Tuesday, April 19 7:00 pm - 11:00 am

Dismantle Hours:

Wednesday, April 20 3:00 pm - 8:00 pm

Tabletop Registration Fees:*

	Thru 3/20/10	After 3/20/10
*IMAPS/ACerS Member	\$550	\$650
Non-Member	\$700	\$800
*Corporate Members		

Included with your registration:

- one (1) six foot draped table
- two (2) chairs
- carpeting
- one (1) Technical Proceedings CD-ROM
- one (1) List of Attendees*
- two (2) Booth Personnel

**Sent after the event.*

Additional booth personnel are welcome at an extra cost of \$50 per person. Registrations for the full conference are not included, but are available at an additional cost.

Shipments are made to the Hotel directly. You save money because no service contractor is involved!

Housing

OVTA is about 60 miles from from Haneda Airport. OVTA itself has accommodation the facility. Many hotels are available around OVTA.

http://www.ovta.or.jp/en/area_7.html

Marketing Feature Available for Exhibitors

IMAPS offers all exhibitors the option of providing an unlimited amount of pages of company products, services and contact information to be included in the Technical Proceedings CD-ROM. These CD-ROMs are provided to all technical conference attendees and are for sale through IMAPS to all industry professionals.

This unique feature will promote an unlimited amount of promotional material for the Exhibitor's products and abilities much longer than just the Conference. **There is no charge for this optional feature, but the deadline is firm.**

Submissions must be sent electronically in one (1) file, either PDF or Word, that is easy to open, not password-protected and in a logical format. Any materials not sent in the required format or that arrive after the deadline, may not appear on the CD-ROM. Send files to abell@imaps.org on or before March 19, 2010.

Organizing Committee

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